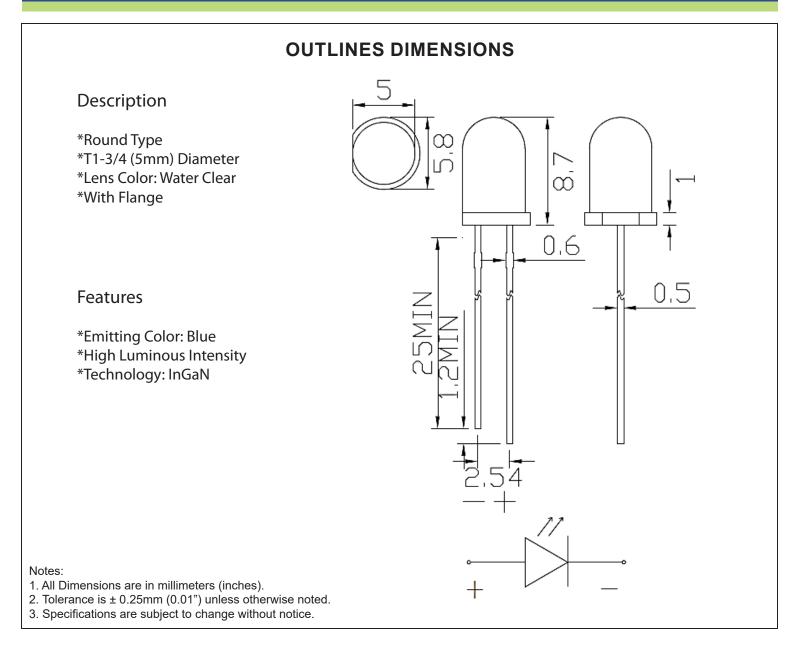


### SPECIFICATIONS

# CLA50B2C



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle
CLA50B2C	InGaN	Blue	Water Clear	20°



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## **ABSOLUTE MAXIMUM RATINGS**

## (TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Power Dissipation	PD	100	mW	
Pulse Current Forward Current	lfp	60	mA	
Continuous Forward Current	lF	30	mA	
Reverse Voltage	Vr	5	V	
Operating Temperature Range	Topr	-25~+85	°C	
Storage Temperature Range	Тѕтс	-30~+85	°C	
IFP = Pulse Width $\leq$ 10 ms, Duty Ratio $\leq$ 1/10. Soldering Condition: 260 °C/ 3sec				

## OPTICAL-ELECTRICAL CHARACTERISTICS

Value **Test Condition** Parameter Symbol Unit Min Тур Max 4000 6000 Luminous Intensity Iv I<sub>F</sub> = 20mA mcd Forward Voltage I⊧ = 20mA 3.0 3.4 V VF \_ **Reverse Leakage Current** 10  $V_R = 5V$ \_ IR \_ μA **Viewing Angle**  $2\theta 1/2$ I⊧ = 20mA 20 \_ \_ deg 465 470 I⊧ = 20mA **Dominant Wavelength** λD nm

\*Tolerance of viewing angle: -10 / +5 deg.



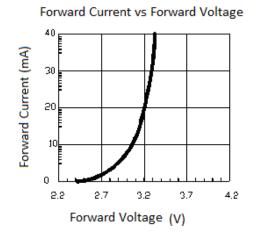
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2

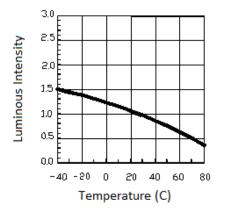
# (TA=25°C)



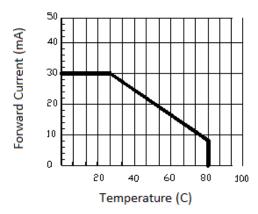
### **OPTICAL CHARACTERISTIC CURVES**

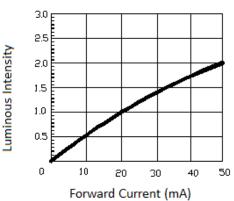


#### Luminous Intensity vs Ambient Temperature



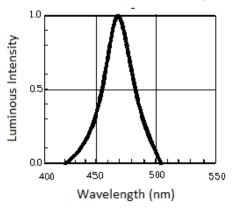
Forward Current vs Ambient Temperature

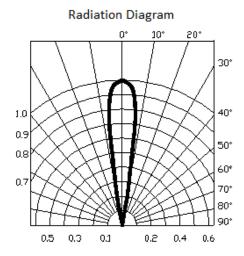




Forward Current vs Luminous Intensity

Luminous Intensity vs Wavelength







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## SOLDERING CONDITIONS – LAMP TYPE LED

\* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

\* Recommended soldering conditions

Dip Soldering				
Pre-Heat	100 °C Max			
Pre-Heat Time	60 Second Max			
Solder Bath Temperature	260 °C Max			
Dippng Time	5 Second Max			
Dipping Position	No lower than 3mm from the base of the epoxy			

Hand Soldering				
	3mm Series	Others		
Temperature Soldering Time Position	300 °C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 °C Max 3 Second Max No closer than 3mm from the base of the epoxy		

\* Do not apply any stress to the lead. Particularly when heated.

- \* The LED must not be repositioned after soldering.
- \* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- \* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.
- \* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- \* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.



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